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(54) **Dielectric resonator and filter with low permittivity material**

(57) A resonator cavity (50) for supporting a plurality of resonant modes and filtering electromagnetic energy includes a cavity (51) and a resonator element (58) with a mounting flange (57). The cavity is defined by a top end wall (52), a bottom end wall (53) and a sidewall (54) and has a longitudinal axis (A) along its length is defined. The resonator element is positioned within the cavity along the longitudinal axis and includes a mounting flange. The resonator element is only in physical contact with the cavity through the mounting flange at a mounting location and where at least one resonant mode of the electromagnetic energy exhibits a local minima.
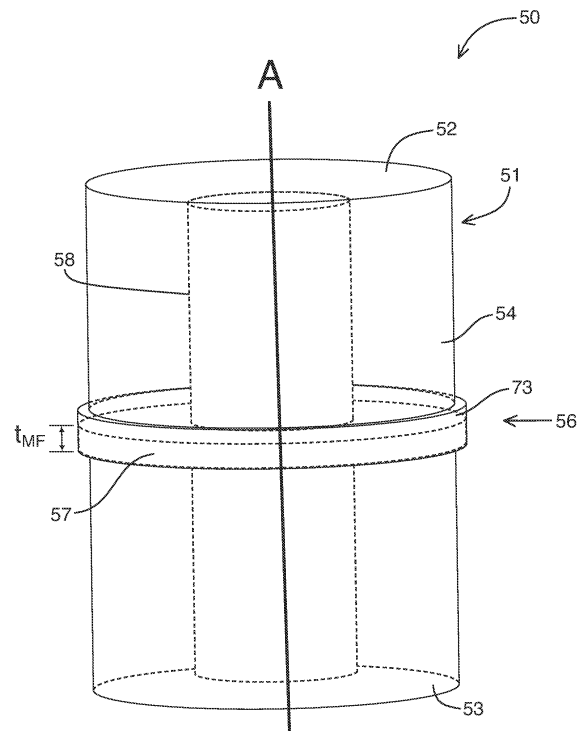
FIG. 5

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Description

FIELD

[0001]   The embodiments described herein relate generally to microwave band pass filters and more particularly to dielectric resonators and filters.

BACKGROUND

[0002]   A microwave filter is an electromagnetic circuit that can be tuned to pass energy at a specified resonant frequency. Accordingly, microwave filters are commonly used in telecommunication applications to transmit energy in a desired band of frequencies (i.e. the passband) and to reject energy at unwanted frequencies (i.e. the stopband) that fall outside of the desired band. In addition, a microwave filter should preferably meet certain performance criteria such as insertion loss (i.e. the minimum loss in the passband), loss variation (i.e. the flatness of the insertion loss in the passband), rejection or isolation (the attenuation in the stopband), group delay (i.e. related to the phase characteristics of the filter) and return loss (i.e. related to the ratio from the reflected and incident power).

[0003]   When the material type and the size of the resonators for the filter are chosen, the Q (i.e. quality) factor for the filter is set. The Q factor has a direct effect on the amount of insertion loss and pass-band flatness of the realized microwave filter. In particular, a filter having a higher Q factor will have a lower insertion loss and sharper slopes (i.e. a more "square" filter response) in the transition region between the passband and the stopband. In contrast, filters which have a low Q factor have a larger amount of energy dissipation due to larger insertion loss and will also exhibit a larger degradation in band edge sharpness. Examples of high Q factor filters include waveguide (hollow cavity) and dielectric resonator filters that have Q factors on the order of 8,000 to 15,000. An example of a low Q factor filter is a coaxial resonator filter that typically has a Q factor on the order of 2,000 to 5,000.

[0004]   Dielectric material with high relative permittivity, or a high relative dielectric constant (i.e. typically a dielectric constant greater than 20) are widely used to form microwave/RF resonators and filters. Permittivity is a physical quantity that determines the ability of a material to polarize in response to an electromagnetic field, and thereby reduces the total electromagnetic field inside the material. Thus, permittivity relates to a material's ability to transmit (or "permit") an electromagnetic field.

[0005]   Due to the fact that the materials of the various components are dielectric materials, they are very poor in conducting heat. Thus, in high power applications, the temperature of dielectric resonators can be very high, which can cause serious operational difficulties especially in a highly constrained mechanical design space.

SUMMARY

[0006]   The embodiments described herein provide in one aspect, a resonator cavity for supporting a plurality of resonant modes and filtering electromagnetic energy, said resonator cavity comprising:

(a) a cavity defined by a top end wall, a bottom end wall and a sidewall, said cavity having a longitudinal axis along which the length of the cavity is defined;

(b) a resonator element having a top end and a bottom end, said resonator element positioned within the cavity along the longitudinal axis of the cavity along which the length of the resonator body is also defined;

(c) the resonator element also including a mounting flange for coupling the resonator element to the cavity at a mounting location along the length of the resonator element;

(d) the cavity and the resonator element having dimensions selected so that the electromagnetic energy associated with the resonator cavity is defined by an electromagnetic field pattern that substantially repeats itself at least twice along the length of the resonator; and

wherein the resonator element is only in physical contact with the cavity through the mounting flange at the mounting location where at least one resonant mode of the electromagnetic energy exhibits a local minima.

[0007]   Further aspects and advantages of the embodiments described herein will appear from the following description taken together with the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0008]   For a better understanding of the embodiments described herein and to show more clearly how they may be carried into effect, reference will now be made, by way of example only, to the accompanying drawings which show at least one exemplary embodiment, and in which:

[0009]   FIG. 1 is a cross-sectional view of a prior art TM mode dielectric resonator assembly;

[0010]   FIG. 2 is a schematic diagram showing the orthogonal TE modes of a prior art microwave multimode resonator assembly;

[0011]   FIG. 3 is a top perspective view showing a prior art dual mode HE filter assembly;

[0012]   FIG. 4 is cross-sectional view of a prior art resonator element and support mounting assembly;

[0013]   FIG. 5 is a side perspective view of an exemplary resonator cavity;

[0014]   FIG. 6 is a cross-sectional view of another exemplary resonator cavity;

[0015] FIG. 7A is a graphical representation of one exemplary electromagnetic field pattern for the excited resonator cavity of FIG. 5;

[0016] FIG. 7B is a graphical representation of another exemplary electromagnetic field pattern for the excited resonator cavity of FIG. 5;

[0017] FIG. 8 is a cross-sectional side view of an exemplary resonator assembly comprising the resonator cavity of FIG. 5;

[0018] FIG. 9A is a top perspective view of the spring element of FIG. 8;

[0019] FIG. 9B illustrates a cross-sectional views of the wave washer of FIG. 9A along the dashed line AA' without an applied load;

[0020] FIG. 9C illustrates a cross-sectional views of the wave washer of FIG. 9A along the dashed line AA' with an applied load;

[0021] FIG. 10A is an enlarged cross-sectional view of the resonator assembly of FIG. 8 showing the position of the wave washer of FIG. 9A prior to engagement of the lid with the enclosure of FIG. 8;

[0022] FIG. 10B is an enlarged cross-sectional view of the resonator assembly of FIG. 8 showing the position of the wave washer of FIG. 9A after engagement of the lid with the enclosure of FIG. 8; and

[0023] FIG. 11 is a top perspective view of an exemplary filter assembly comprising three of the resonator assemblies of FIG. 8.

[0024] It will be appreciated that for simplicity and clarity of illustration, elements shown in the figures have not necessarily been drawn to scale. For example, the dimensions of some of the elements may be exaggerated relative to other elements for clarity. Further, where considered appropriate, reference numerals may be repeated among the figures to indicate corresponding or analogous elements.

DETAILED DESCRIPTION

[0025] It will be appreciated that numerous specific details are set forth in order to provide a thorough understanding of the exemplary embodiments described herein. However, it will be understood by those of ordinary skill in the art that the embodiments described herein may be practiced without these specific details. In other instances, well-known methods, procedures and components have not been described in detail so as not to obscure the embodiments described herein. Furthermore, this description is not to be considered as limiting the scope of the embodiments described herein in any way, but rather as merely describing the implementation of the various embodiments described herein.

[0026] Referring now to FIG. 1, a prior art TM mode dielectric resonator assembly 10 is illustrated. It includes a housing 11 having a lid/top end wall 12, a bottom end wall 14 and a cylindrical sidewall 13. The walls are metallic and together form a cavity 15. The resonator assembly 10 can be tuned through the use of a tuning screw

19, arranged in the lid 12. Resonator element 16 is positioned within the cavity 15 through the use of a ring 17 formed with an inner annular shoulder for receiving the dielectric resonator element 16 as shown. The dielectric resonator element 16 can be fastened within the annular shoulder of the ring 17 by an adhesive or by clamping action. The ring 17 is attached to the bottom end wall 14 of the housing 11 by screws 18. The spacing between the resonator element 16 and the bottom end wall 14 can decrease current induced in the bottom end wall 14 and thereby result in a higher Q for the assembly 10. The TM mode dielectric resonator assembly 10 has wider tuning range and simpler resonator arrangement with respect to the standard $TE_{01\delta}$ mode.

[0027] However, the extra space between the resonator element 16 and the bottom end wall 14 can also result in lack of heat conduction from the resonator element 16 to the housing 11. This can lead to undesirable run-away effects and overheating, under high power condition. Also, the TM mode dielectric resonator assembly 10 offers a lower Q-factor than the standard $TE_{01\delta}$ arrangement and no suitable material has been found to recover the lowered Q factor. Furthermore, the range of spurious-free frequency is reduced with respect to the standard $TE_{01\delta}$ arrangement. Consequently, the resonator assembly 10 can only be considered for low frequency application such as L-Band and S-Band since it is not suitable for higher frequency band.

[0028] Referring now to FIG. 2, a prior art TE multi-mode resonator assembly 20 is shown. The resonator assembly 20 includes a resonator element 21 and a housing 22. The resonator assembly 20 also includes a first tuning screw 23 for tuning a first mode m1, a second tuning screw 24 for tuning a second mode m2, and a coupling screw 25 for varying the coupling of energy between the two orthogonal excitation modes m1 and m2 of the resonator element 21. Coupling means 26 and 27 are included for inlet and outlet cavities for either coupling microwave energy into an inlet cavity or extracting it from an outlet cavity. Furthermore, the resonator element 21 is essentially planar, having a thickness and an outline in the form of a polygon with n sides and n vertices which are short-circuited together by the conducting housing as shown.

[0029] In FIG. 2, the resonator element 21 has an outline in the form of a parallelogram with four sides and four vertices. The vertices are truncated or rounded so as to fit closely to the shape of the housing. The resonator element is in mechanical and electrical contact with the housing that enables the resonator element to be positioned exactly and reproducibility inside the resonator cavity and without the need for a support element that is necessary in the standard TE mode resonator assemblies (see FIG. 3). The mechanical contacts also facilitate the transfer of heat from the resonator element to the housing. Furthermore, the two orthogonal modes m1 and m2 of the resonator assembly are excited in TE mode as opposed to the HE mode. They are orthogonal merely

because of the square shape of the housing and the parallelepipedal shape of the resonator element.

[0030] However, this configuration still suffers from deficiency of heat transfer between the resonator element **21** and the housing **22** due to the spacing between them. Although having the dielectric resonator element **21** touching the metal housing **22** at the four vertices helps to dissipate the heat from the dielectric resonator element, doing so also degrades the Q-factor. The mounting of the dielectric resonator element **21** inside the cavity can also be complicated and requires very precise machining and mechanical processes to minimize bond line thickness. In addition, the TE dual mode operation of the resonator assembly **20** will reduce the power handling capability due to the higher power dissipation inside the dielectric resonator element with respect to a single mode cavity. Thus the achievable Q factor is likely to be lower than a standard TE mode resonator assembly with a cylindrical hollow invar cavity, especially at high frequency such as the Ku Band for satellite communication system.

[0031] In other standard resonator assemblies, resonator elements can be positioned within housings and held in position by an insulating mount in the form of pellets or columns of insulating material having low dielectric losses, such as polystyrene or PTFE. Such mounts have numerous mechanical and operational drawbacks both during assembly and during operation of the known filter. An example of another standard resonator assembly using the above-mentioned mounts is the dual-mode resonator assembly.

[0032] Referring now to FIG. 3, a prior art dual-mode resonator assembly **30** is shown. The dual-mode resonator assembly **30** comprises four dielectric resonators **32** positioned within four cavities **31** formed by a sidewall **33** and a bottom wall **34**. Probes **35** and iris openings **36** are provided for coupling adjacent and non-adjacent modes of the neighboring resonators **32**. Tuning screws **37** are provided to protrude through sidewalls **33** of cavities **31** for provoking derivative orthogonal modes and for determining the degree of coupling between orthogonal modes within a resonator. Port **39** is shown with an inner conductive probiscus **38** extending into the cavity **31**.

[0033] The prior art dual-mode resonator assembly **30** permits filter mass and size reduction in comparison with a single mode technology. However power dissipation is greatly confined inside the puck and will almost double with respect to a single mode resonator, thus reducing the power handling of the dual-mode structure.

[0034] Furthermore, although not shown in FIG. 3, the resonator **32** is kept in place within cavity **31** by a material having a low dielectric constant, such as styrofoam™, or by a metal or dielectric screw (or other means) disposed along the vertical cylindrical axis of the resonator **32** and cavity **31**. The insertion loss of the filter is determined by the Q-factors of the individual dielectric resonator **32** loaded cavities **31**, which in turn depends upon the loss of the dielectric resonator **32** material and the material

used to position and support the resonator **32** within the cavity **31**. This leads to a similar problem in terms of the bonding and heat flow management of the standard $TE_{01\delta}$ design (FIG. 4), except that the problem is further amplified in the case of a dual-mode resonator assembly **30** . This is because the dissipation inside the resonator of a dual-mode structure is nearly double that of a single mode design. To realize a practicable high power filter using such a design approach requires careful navigation within a complex design space, which may be prohibitive at high frequencies like Ku-Band.

[0035] FIG. 4 illustrates a standard mounting technique for the $TE_{01\delta}$ mode resonator assembly. A typical dielectric resonator assembly with high Q-factor using $TE_{01\delta}$ mode includes a cylindrical resonator element **44** made from a dielectric material that has a high dielectric constant (i.e. a dielectric constant greater than 20), and a high Q factor. The dielectric resonator element **44,** usually called a "puck", is mounted on top of a support **46** made of lower dielectric constant material such as polystyrene, quartz, or other suitable material. In turn, the support is held in place by a pedestal **48** that connects to the base of the cavity wall structure (not shown).

[0036] This prior art mounting technique is usually employed in a highly constrained mechanical design space. The cantilevered structure formed by the resonator element **44,** the support **46** and the pedestal **48,** is susceptible to high loading under lateral vibration or pyrotechnic shock forces when space applications are considered. The choice of dielectric materials and geometry are dominated by RF considerations resulting in limited control over moments and strength properties of the structure. These RF design constraints offer few fastening options for the resonator element **44** and the support **46**. Accordingly, these components are usually held in place via bonded lines **42,** which can be problematic. The bonding material must exhibit sufficient adhesion over the full operational temperature range. The cohesive strength of the bond lines **42** must also be adequate and this property is sensitive to the bond line thickness. However, the bond line thickness also affects both the transfer of heat out of the resonator element and the additional RF dissipation within the bond line. Further, thermally induced shear stresses on the bonded surfaces (resulting from disparate coefficients of thermal expansion) must be acceptable and it is dependent on bond line thickness as well.

[0037] Heat flow management is bounded by the parameters such as, but not limited to, heat dissipation, thermal conductivity of the materials, and various section surface sizes and shapes (which effects the thermodynamic properties of the components). However, varying these factors are likely to have a concomitant effect on the Q factor of the overall resonator assembly. Of particular interest is the bonding material used for the bond lines, which can be treated as a series heat conduction path and a heat dissipation source.

[0038] An important issue to consider is the potential formation of adiabatic barriers, wherein modest heat dis-

sipation within a very small volume can result in a significant, but localized, temperature rise. When such a hot spot is in series with heat flow, the base level for all upstream heat sources is raised accordingly. The Q factor will not suffer if the electromagnetic field is confined within the resonator element. To maximize the confinement of the electromagnetic field within the resonator element, it is generally needed to minimize the resonator element's contact area to the surrounding walls or the enclosure, which leads to poor heat dissipation. The problem with the trade-off of heat flow management and the Q factor has not been addressed appropriately or optimized according by the prior art resonator assemblies shown above.

[0039] In regard to heat flow management for dual-mode resonator assemblies such as the resonator assembly 30 shown in FIG. 3, it is noteworthy that dielectric dual-mode technologies allow for filter mass and size reduction in comparison with a single mode technology. However, power dissipation is greatly confined inside the puck and nearly doubles with respect to a single mode resonator assembly. Heat dissipation remains an even more challenging issue thus effectively reducing the power handling of the dual-mode structure.

[0040] Referring now to FIG. 5, illustrated therein is an exemplary resonator cavity **50** that includes a cavity **51**, a resonator element **58**, and a mounting flange **57**. Conventional tuning screws and coupling means may be utilized within the resonator cavity **50** as will be discussed.

[0041] The cavity **51** is defined by a top end wall **52**, a bottom end wall **53** and a sidewall **54** that is preferably cylindrical as shown in FIG. 5. Also, cavity **51** has a longitudinal axis A along which the length of the cavity **51** is defined. It should be understood that while the present description will focus on a cylindrical cavity **51** with a circular cross-section, cavity **51** could instead be implemented having any shape and cross-section. Cavity **51** is made from a metallic material.

[0042] The resonator element **58** includes a generally cylindrical dielectric rod with a circular cross-section that is positioned within the cavity **51** along the longitudinal axis A of the cavity **51**. The length of the resonator element **58** is also defined along the longitudinal axis A. It should be understood that the generally cylindrical dielectric rod of the resonator element **58** could also have an elliptical, square, or polygonal cross-section. In such cases, it should be also understood that the mounting flange **57** would be suitably shaped to surround the dielectric rod of the resonator element **58**. The generally cylindrical dielectric rod of the resonator element **58** is made from a dielectric material with a low relative permittivity (i.e. a low dielectric constant of less than 20) and a low loss tangent.

[0043] The resonator element **58** also includes a mounting flange **57** that is preferably a flat annular (i.e. ring-shaped) extension with a thickness of t_{MF} and an outer radius slightly larger than the inner radius of the cavity **51** as shown in FIGS. 5, 8, 10A and 10B. However,

while the lateral cross-section of the mounting flange **57** is preferably rectangular (FIGS. 10A, 10B), it should be understood that the lateral cross-section could also be circular, square, triangular, etc. Also while the mounting flange **57** is preferably formed in a continuous ring so that it completely surrounds the resonator element **58**, the mounting flange **57** could instead be formed to extend along only a portion of the circumference of resonator element **58**. Also, while mounting flange **57** is preferably formed to be symmetrical around the longitudinal axis A, it may also be unsymetrically formed. The mounting flange **57** is preferably made from a dielectric material with a low relative permittivity and a low loss tangent.

[0044] Mounting flange **57** is preferably integrally formed with the rest of resonator element **58**. However, it should be understood that it is possible to manufacture the mounting flange **57** separately and to then couple mounting flange **57** to the rest of resonator element **58** using bonding or other conventional means. However, in such a case, degradation of Q will result making such an arrangement less desirable.

[0045] As shown in FIG. 5, the resonator element **58** is positioned within and coupled to the cavity **51** through the mounting flange **57** at a mounting location **56**. Preferably the mounting flange **57** is secured within the cavity **51** using a spring element **78** and counter bore **73** configuration as will be further described in further detail with respect to FIGS. 8, 10A and 10B. The resonator element **58** is mounted within the cavity **51** using various mechanical methods without significantly compromising performance or Q factor. For example, resilient epoxy or a resilient spring element **78** can be used.

[0046] The preferred mounting location **56** for the exemplary resonator assembly **50** of FIG. 5 is where at least one resonant mode of the electromagnetic energy exhibits a local minima. Accordingly, the resonator element **58** is only in physical contact with the cavity **51** through the mounting flange **57** where at least one resonant mode of the electromagnetic energy exhibits a local minima. A local minima can occur at a variety of points along the length of the resonator element **58** depending on the repetition rate of the electromagnetic field pattern along the length of the resonator, as will be discussed in more detail in relation to FIGS. 7A and 7B.

[0047] FIG. 5 illustrates how the mounting flange **57** is positioned within resonator cavity **50** in the presence of an electromagnetic field pattern that substantially repeats itself twice along the length of the resonator. As will be further discussed, positioning of the mounting flange **57** within resonator cavity **50** will vary according to the electromagnetic field pattern present within the resonator cavity **50** (e.g. see FIG. 7B).

[0048] In the exemplary configuration shown in FIG. 5, it is assumed that the dimensions of the cavity **51** and the resonator element **58** have been selected so that the electromagnetic energy associated with the resonator cavity **58** is defined by an electromagnetic field pattern that substantially repeats itself twice along the length of

the resonator (FIG. 7A). In this situation, the preferred mounting location **56** for the exemplary resonator assembly **50** of FIG. 5 is at the approximate midpoint of the length of the resonator element **58** where at least one resonant mode of the electromagnetic energy exhibits a local minima. Accordingly, the resonator element **58** is only in physical contact with the cavity **51** through the mounting flange **57** at the circumferential region at the approximate midpoint of the length of the resonator element **58** as shown.

[0049] The top and bottom ends of resonator element **58** are not in physical contact with the top or bottom walls **52** and **53** of the cavity **51.** Rather, a space gap is formed between the top end of the resonator element **58** and the top end wall **52** of the cavity **51** and another space gap is formed between the bottom end of the resonator element **58** and the bottom end wall **53** of the cavity **51.** These space gaps are designed to provide the resonator cavity **50** with thermal stability, that is the ability to maintain a fixed resonator frequency while the temperature of the resonator cavity **50** changes. This is because the space gaps allow space for the top and/or bottom end walls of the cavity **51** to be deformed into when acted on by an external force in the presence of temperature changes (e.g. as discussed in U.S. Patent No. 6,535,087 to Fitzpatrick et al.) allowing for temperature compensation.

[0050] As will be discussed in further detail in relation to FIGS. 7A and 7B, certain resonant modes of the electrical field generated by the resonator assembly **50** exhibit one or more local minimas along the length of the resonator element **58**. The resonator element **58** is only in physical contact with the cavity **51** through the mounting flange **57** at the appropriate mounting location **56**. The mounting location **58** is selected to be along the length of the resonator element **58** where certain resonant modes of the generated electromagnetic energy exhibit a local minima.

[0051] Referring now to FIG. 6, another exemplary resonator cavity **60** is illustrated including a cavity **61,** a resonator element **68** and a mounting flange **67**. Conventional tuning screws and coupling means may be utilized within the resonator cavity **60.**

[0052] The cavity **61** is defined by a top end wall **62,** a bottom end wall **63** and a sidewall **64** and is typically cylindrical as shown in FIG. 6. Also, cavity **61** has a longitudinal axis B along which it's length is defined. As discussed above, It should be understood that while the present description will focus on a cylindrical cavity **61** with a circular cross-section, cavity **61** could instead be implemented having any shape and cross-section. Cavity **61** is made from a metallic material.

[0053] The resonator element **68** is positioned within the cavity **61** along longitudinal axis B and includes a generally cylindrical dielectric rod. The length of the resonator element **68** is also defined along the longitudinal axis B. It should be understood that the generally cylindrical dielectric rod of the resonator element **68** could

also have a circular, elliptical or polygonal cross-section. The resonator element **68** is made from a dielectric material with a low relative permittivity (i.e. low dielectric constant) and a low loss tangent.

[0054] The resonator element **68** also includes a mounting flange **67** which is preferably a slightly sloped annular (i.e. ring-shaped) extension with a radius that is generally less than that of the cavity **61** as shown. However, the mounting flange **67** could also have other various shapes. As discussed above, while the lateral cross-section of the mounting flange **67** is preferably sloped as shown it should be understood that the lateral cross-section could also be circular, square, triangular, etc. Also while the mounting flange **67** is preferably formed in a continuous ring so that it completely surrounds the resonator element **68,** the mounting flange **67** could instead be formed to extend along only a portion of the circumference of resonator element **68.** Also, while mounting flange **67** is preferably formed to be symmetrical around the longitudinal axis A, it may also be unsymmetrically formed.

[0055] For structural strength, mounting flange **67** is preferably thicker at the region where it meets the generally cylindrical rod of resonator element **68** to ensure that operational vibrations do not lead to cracking or other damage to the resonator element **68.**

[0056] Also as discussed, above in relation to the exemplary resonator cavity 50 of FIG. 5, the mounting flange **67** is preferably integrally formed with the generally cylindrical rod of the resonator element **68.** However, it should be understood that it is possible to manufacture the mounting flange **67** separately and to then couple mounting flange **67** to the rest of resonator element **68** using bonding or other conventional means. However, in such a case, degradation of Q will result making such an arrangement less desirable.

[0057] As shown in FIG. 6, the complete bottom surface of the resonator element **68** which consists of the bottom surface of the generally cylindrical rod and the bottom surface of the mounting flange **67,** is coupled to the bottom end wall **63** of the cavity **61**. Various known methods may be used for mounting the bottom surface of the resonator element **68** to the bottom end wall of the cavity **61** such as such as epoxy, a clamping collar, a metal spring mechanism or a combination thereof.

[0058] For illustrative purposes, the combination of a metal clamping collar **69** and spring **66** mechanism is shown in FIG. 6. Specifically, a clamping collar **69** is provided which can be positioned over an outer portion of the mounting flange **67** of the resonator element **68** and secured to the bottom of the cavity **61** using bolts **59** as shown. When the clamping collar **69** is bolted into place on the bottom of the cavity **61,** the spring **66** of the clamping collar **69** is forced down onto the the mounting flange **67** securing the resonator element **68** into place through deflection pressure exerted by the spring **66** on the edge of the mounting flange **67**. The clamping collar may be made of metal or dielectric material.

[0059] Alternatively, the clamping collar **69** can be used without a spring **66** to secure mounting flange **67** in place. In order to do so the bottom surface of the portion of the clamping collar **69** that overhangs the mounting flange **67** is shaped to contact the mounting flange **67** along a contact region to secure mounting flange **67** and resonator element **68** in place. In that configuration, clamping collar **69** is also provided with a spring constant so that it acts as a spring itself to provide deflection pressure on the edge of the mounting flange **67.**

[0060] The top end of resonator element **68** is not in physical contact with the cavity **61** and instead a space gap is formed between the top end of the resonator element **68** and the top end wall of the cavity **61** providing similar temperature compensation facility as discussed in relation to the resonator cavity **50** of FIG. 5 above.

[0061] The resonator cavity **60** of FIG. 6 exhibits certain operational advantages, although they are different from the resonator cavity **50** of FIG. 5. Specifically, since the bottom surface of the resonator element **68** which consists of the bottom surface of the generally cylindrical rod and the bottom surface of the mounting flange **67,** is in complete surface contact with the bottom end wall of cavity **61,** resonator cavity **60** of FIG. 6 is provided with minimal thermal resistance and an extremely effective heat sink from the low dielectric constant resonator element **68** to ground. This thermal grounding makes the resonator cavity **60** particularly suitable for higher power applications since the heat created can be effectively dissipated by the resonator cavity **60** structure.

[0062] Also, since the electromagnetic field pattern repeats itself at least twice along the length of the resonator element **68** means that high magnetic field regions are located at the ends of the resonator element **68.** The resonator element **68** which has a low dielectric constant is only is in contact with the cavity **61** in one of these high magnetic field regions. This minimizes the impact on quality factor Q. In contrast, it is not possible to use typical prior art resonator cavities that use a resonator element **68** with lower dielectric constant for high power applications since the quality factor Q will be much more drastically reduced.

[0063] However, the resonator cavity **50** shown in FIG. 5 typically has a higher Q factor than the resonator cavity **60** of FIG. 6. This is because the dielectric resonator element **58** in FIG. 5 is in physical contact with the cavity **51** only where the mounting flange **57** and the sidewall **54** are in contact. This location is where the electromagnetic field is at a minimum as will be discussed in more detail in relation to FIGS. 7A and 7B. Therefore, while a certain amount of heat dissipation from the resonator element **58** to the cavity **51** through the mounting flange **57** is provided, less electromagnetic energy is transferred to the cavity sidewall **51** than is the case in the resonator cavity **60** of FIG. 6 where the resonator element **58** contacts the cavity **61** at the bottom of the sidewall **64.**

[0064] Referring now to FIG. 7A and 7B, the electromagnetic field pattern assoicated with two excited exem-

plary resonator cavities **50** is shown.

[0065] In FIG. 7A, the dimensions of the cavity **51** and the resonator element **58** have been selected so that the electromagnetic energy associated with the resonator cavity **58** is defined by an electromagnetic field pattern that substantially repeats itself twice along the length of the resonator element **58.** In this situation, the preferred mounting location for the exemplary resonator assembly **50** of FIG. 5 is at the approximate midpoint of the length of the resonator element **58** where at least one resonant mode of the electromagnetic energy exhibits a local minima. As shown, the mounting flange **57** is secured in place within the cavity **51** at this mounting location using a spring element **78** positioned within the counterbore **73** of the cavity **51** as will be further described in relation to FIGS. 8, 10A and 10B.

[0066] As shown, the electromagnetic field pattern around the top half of the resonator element **58** is repeated around the bottom half of resonator element **58.** Also, the electromagnetic field radiating outward from the approximate midpoint of the longitudinal length of the resonator element **58** exhibits a minima in between the repeated electromagnetic patterns as shown. The specific dimensions of the cavity **51** and the resonator element **58** are selected to support a desired repetition of the electrical field pattern and to enhance the quality factor Q without degradation of the spurious free frequency range (i.e. without the excitation of other resonant modes). Specifically, the length of the resonator **58** and ratio of the cross-section size and length of the resonator **58** are selected for this purpose. The desired length of the resonator **58** is a result of such optimization using commercially available electromagnetic modeling software.

[0067] In FIG. 7B, the dimensions of the cavity **51** and the resonator element **58** have been selected so that the electromagnetic energy associated with the resonator cavity **58** is defined by an electromagnetic field pattern that substantially repeats itself three times along the length of the resonator element **58.** Here, the preferred mounting location for the exemplary resonator assembly **50** of FIG. 5 is at approximately one third or two thirds along the length of the resonator element **58** where at least one resonant mode of the electromagnetic energy exhibits a local minima. Again, the mounting flange **57** is secured in place within the cavity **51** at this mounting location using a spring element **78** positioned within the counterbore **73** of the cavity **51** as will be further described in relation to FIGS. 8, 10A and 10B.

[0068] As shown, the electromagnetic field pattern around the top third of the resonator element **58** is repeated in the middle and at the bottom third of resonator element **58.** Also, the electromagnetic field radiating outward at approximately one third or two thirds along the length of the resonator element **58** exhibits a minima as shown. As discussed above, the specific dimensions of the cavity **51** and the resonator element **58** are selected to support a desired repetition of the electrical field pattern and to enhance the quality factor Q without degra-

dation of the spurious free frequency range (i.e. without the excitation of other resonant modes).

[0069] While FIGS. 7A and 7B illustrate the situation where the electromagnetic energy associated with the resonator cavity **58** is defined by an electromagnetic field pattern that substantially repeats itself two or three times along the length of the resonator element **58,** it should be understood that the electromagnetic energy associated with the resonator cavity **58** may alternatively be defined by an electromagnetic field pattern that substantially repeats itself any number of times along the length of the resonator element **58**. A preferred mounting location will then correspond to one of the positions along the resonator element **58** where at least one resonant mode of the electromagnetic energy exhibits a local minima.

[0070] The circumferential contact region where the mounting flange **57** and the sidewall **54** of the cavity **51** contact, exhibits a slightly stronger electromagnetic field then other areas of the sidewall. This can lower the design Q factor for the resonator cavity **50**. However, if the contact region were to be elsewhere, such as through the bottom of the resonator element **58** and the end wall of the cavity **51** as shown in FIG. 6, then more electromagnetic energy would leak into the cavity walls, resulting in an even lower Q factor. This is because the electromagnetic field radiating near the bottom of the resonator element **58** is not at a minima. As discussed below, the dimensions of the cavity **51** and the resonator element **58** are selected so that the electromagnetic energy associated with the resonator cavity **51** is defined by an electromagnetic field pattern that substantially repeats itself a certain number along the length of the resonator.

[0071] Generally speaking, the exemplary resonator cavities **50** are designed so that a large amount of the electromagnetic energy is confined within the resonator element **58,** with some electromagnetic energy being transferred out of the resonator element **58** into the cavity **51**. However, little electromagnetic energy reaches sidewall **54** of the cavity **51,** which is desirable.

[0072] FIG. 8 illustrates a cross-sectional view of an exemplary resonator assembly **70** that includes a spring element **78,** a lid **71,** an enclosure **72** and the resonator cavity **50** of FIG. 5.

[0073] The cavity **51** of the resonator cavity **50** is a cylindrical space defined by the inner surfaces of the lid **71** and the enclosure **72**. The lid **71** provides the upper half of the resonator cavity **51,** namely a top end wall and the top half of the cylindrical sidewall. The enclosure **72** holds the resonator element **58** and provides the bottom half of the cavity **51,** namely a bottom end wall and the bottom half of the cylindrical sidewall.

[0074] The enclosure **72** further includes a counter bore **73** for receiving and supporting the mounting flange **57** (see FIG. 10A and 10B). The counter bore **73** is formed as a small rectangular radial protrusion in the side of the enclosure **72**. The counter bore **73** is sized to receive the outer edge of the mounting flange **57** as well as a spring element **78** (see FIGS. 10A and 10B).

[0075] The exemplary resonator assembly **70** shown has been designed for application to an electromagnetic field pattern that substantially repeats itself twice along the length of the resonator element **58**. As discussed, the preferred mounting location for the exemplary resonator assembly **50** of FIG. 8 will be at the approximate midpoint of the length of the resonator element **58** where at least one resonant mode of the electromagnetic energy exhibits a local minima. However, it should be understood that the clamping mechanism of the assembly of FIG. 8 could equally be applied in the context of an electromagnetic field pattern that substantially repeats itself three or more times along the length of the resonator element **58**. This could be done by rearranging the relative dimensions of the lid **71** and the enclosure **72,** and the location of the counter bore **73** so that the mounting location for the mount flange corresponds to a position along the resonator element **58** where at least one resonant mode of the electromagnetic energy exhibits a local minima.

[0076] As shown in FIG. 8, in this case, the lid **71** and the enclosure **72** meet generally at a plane orthogonal to the longitudinal axis A of the cavity **51** and at the approximate midpoint of the length of the resonator element **58**. As will be discussed, this arrangement effectively fixes the resonator element **58** within the resonator cavity **50** through a clamping force that is exerted on the mounting flange **57** by the lid **71** and enclosure **72** through a spring element **78** (e.g. a wave washer), as will be discussed in further detail in relation to FIGS. 10A and 10B.

[0077] The resonator assembly **70** can also include a tuning screw **74** and a coupling screw **76,** as shown. The coupling screw **76** may be used to couple orthogonal modes between the cavities in the case of dual mode operation. Specifically, cross-coupling can be used between non-adjacent modes or cavities.

[0078] The electrical field patterns discussed are desirable because a repeated electromagnetic field pattern facilitates construction of complex elliptic functions which allow for strategic positioning of coupling elements (e.g. tuning screws and irises) to reduce unwanted coupling resulting in better filter performance. Specifically, a coupling screw **76** is shown located on the bottom part of the cavity **71** (FIG. 8) but it can also be located at the top part of the cavity **71** in the same plane as the tuning screw **74**. The ability to position coupling elements at the top and bottom of the cavity **71** without compromising performance provides more design flexibility.

[0079] FIG. 9A, 9B and 9C together illustrate an exemplary spring element **78,** namely a wave washer **78** in more detail. Specifically, FIG. 9B and 9C show a cross sectional view of the wave washer **78** shown in FIG. 9A taken along the line A-A'. The wave washer **78** is made from a metal material characterized by good spring properties. However, it should be understood that the spring element **78** could be implemented using any other type of mechanical device having appropriate spring properties. Other types of mechanical devices may be made of

metal, dielectric or other suitable materials.

[0080]   A wave washer **78** is a type of non-flat washer, having a slight conical shape which gives the wave washer **78** a spring-like characteristic. When a load is applied as shown in FIG. 9C, the wave washer **78** deflects sideways and increases its unloaded outer diameter from d2 (FIG. 9B - no load condition) to the loaded outer diameter d2' (FIG. 9C - with load conditions) according to a specific spring constant. It should be noted that the unloaded inner diameter d1 and the loaded diameter d1' will respond similarly to the load.

[0081]   Referring now to FIG. 10A and 10B, illustrated therein are enlarged views of the interface between the enclosure **72** and the lid **71** of the resonator assembly **70**. FIG. 10A illustrates the interface before the lid **71** is forced down on the enclosure **72** and FIG. 10B illustrates the interface after the lid **71** has been forced down on the enclosure **72**.

[0082]   In assembly, the resonator element **58** is first placed within the enclosure **72** such that the mounting flange **57** is positioned within the counter bore **73** as shown. Then, the wave washers **78** are placed on top of the top surface of the mounting flange **57**. At this point, the wave washers **78** are in a relaxed (i.e. unloaded) state and protruding slightly above the enclosure **72**. The lid **71** is then fastened onto the enclosure **72**, depressing the wave washers **78** into the enclosure **72** and providing a clamping force onto the mounting flange **57** of the resonator element **58**.

[0083]   The clamping force provided this way prevents any potential small scale (e.g. micro) movements resulting from a loosely fixated resonator element **58**, which may lower the performance or damage the device in critical applications. The lid **71** may be locked or clamped or snapped in place on the enclosure **72** by any known method after it is applied onto the enclosure **72**.

[0084]   As shown in FIG. 10A and 10B, the cross section of the lid **71** has a thickness defined by an outer diameter d_{L2} and an inner diameter d_{L1}. The generally cylindrical rod element of resonator element **58** has a diameter d_R as shown and the mounting flange **57** has a thickness of t_{MF}. Also, the counter bore **73** has an outer diameter of d_{CB}. The wave washer **78**, in addition to be characterized by a spring constant, must have a loaded inner diameter d1' generally greater than the diameter of the resonator element d_R, and a loaded outer diameter d2' generally greater than the inner diameter d_{L1} of the lid and less than the diameter d_{CB} of the counter bore.

[0085]   The wave washer **78** is placed between the lid **71** and the mounting flange **57** of the resonator element **58** so that a clamping force is provided to the resonator element **58** to prevent small scale (i.e. micro) movements of the resonator element **58**. However, it should be understood that the wave washer **78** may also be placed between the mounting flange **57** of the resonator element **58** and the enclosure **72**, or both, for similar results.

[0086]   Alternatively, the wave washer **78** may be eliminated if the depth P_{CB} of the counter bore **72** is made to be less than the thickness t_{MF} of the mounting flange **57** of the resonator element **58**.

[0087]   The use of a wave washer **78** can alleviate the thermally induced stresses in the resonator **58** by removing some of the thermal stress between the lid **71** and the dielectric material of the resonator elements **58**. This makes the overall assembly more suitable for space application.

[0088]   The use of wave washers **78** instead of bonding processes to secure a resonator element **58** within a cavity **51** provides a significant assembly process advantage and eliminates the incidence of performance variations due to variations in bond line thickness.

[0089]   The above-described mounting arrangement has a very small impact on the Q factor of the resonator cavity **50**, since the resonator element **58** is mounted within the cavity **51** through the mounting flange **57** at the electromagnetic field minima. As shown in FIGS. 7A and 7B, the electromagnetic field minima is guaranteed by design to be located at the midpoint of the length of the resonator element **58** through careful optimization of the dimension and shape of the resonator element **58** and cavity **51**. Accordingly, the electromagnetic field pattern repeats itself twice along the length of the resonator cavity **50** without comprising the spurious-free range, and allowing for a very high Q factor. This particular mounting structure is applicable to support a plurality of resonant modes and results in lower filter mass and size reduction.

[0090]   Power that is dissipated inside the dielectric material of the resonator element **58** increases with temperature. In the absence of proper thermal management, this can in turn increase RF losses that lead to further increases in temperature, resulting in a run-away effect. The above-noted mounting configuration provides superior power handling capability when compared with prior art mounting techniques such as that shown in FIG. 4 where the resonator element is mounted on a support. The superior power handling capability of the resonator element **58** is due to the fact that less power is dissipated inside the dielectric material of the resonator element **58**, together with less energy stored in the dielectric resonator (FIG. 7B) and the good thermal path provided between the resonator element **58** and the enclosure **72** and the lid **71** at the end walls of the counter bore **73** located at the approximate midpoint of the length of the resonator element **58**.

[0091]   As discussed, in this case where the electromagnetic field pattern repeats itself twice along the length of the resonator element **58**, the electromagnetic field exhibits a local minima within the resonator assembly **70** at the approximate midpoint of the length of the resonator element **58** where the mounting flange **57** is used to couple the resonator element **58** to the enclosure **72**. This minima of the electromagnetic field extends in a plane that is orthogonal to the longitudinal axis A (FIG. 5) of the cavity **51**. This electromagnetic field characteristic offers an opportunity to maximize the quality factor Q for the microwave filter assembly **70** without compromising

the ability to transfer heat away from the resonator elements **58** to the cavities **51**, the enclosure **72** and the lid 71.

[0092] Specifically, since the circumferential region of physical contact between the mounting flange **57** and the sidewall of the cavity **51** is in the same plane as the minima of the electromagnetic field discussed above (i.e. extending in a plane that is orthogonal to the longitudinal axis A (FIG. 5) at the approximate midpoint of the length of the resonator element **58),** the Q factor is not degraded by the heat transfer from the resonator element 58 that occurs along this circumferential region. It should be understood that other methods can be used to fix the dielectric resonator element **58** to the aforementioned desirable circumferential region of the sidewall, such as the usage of a resilient epoxy or other known mechanical spring/wave washers.

[0093] It should be understood that the concept of using low dielectric constant materials for the resonator element **58** and the mounting support such as the spring element **78,** cannot be directly applied to prior art mounting assemblies (FIGS. 1 to 4) because doing so will result in size increase and generation of spurious modes. The presently described configuration is suited for application using low dielectric constant material.

[0094] FIG. 11 illustrates a filter assembly **80** that includes three resonator assemblies **92, 93** and **94** of FIG. 8, an input port **81** and an output port **91**. Each of the resonator assemblies **92, 93** and **94** include a dielectric resonator element 58 made of a material that has a relatively low dielectric constant (e.g. less than 20), a large Q factor, and may have a small coefficient of resonant frequency variation as a function of temperature.

[0095] As described above, each resonator element **58** is mounted to the corresponding resonator cavity **51** though a mounting flange **57.** Coupling between two resonator assemblies can be achieved through the use of irises **82** and/or other known coupling methods such as probes. As conventionally known, irises **82** are slots manufactured on the sidewalls of the enclosure **72** or the lid **71** of each resonator assembly **92, 93** and **94** in order to connect two adjacent resonator assemblies.

[0096] In general, more than one iris **82** can be used to couple energy between resonator assemblies and varying the sizes of each iris can vary the amount of energy transfer between the two adjacent resonator assemblies. Probes can be made from metal rod of various different shapes and they can be mounted between the cavities of the resonator assemblies via slots or hole while remaining electrically isolated from the walls of the enclosure. The amount of energy coupled through depends from the depth of protrusion into each cavity.

[0097] One or two resonator assemblies, typically the first (inlet) and/or the last (outlet), are characterized from an input port **81** or output port **91,** which allow the electromagnetic energy to flow in and out of filter assembly **80.** Input and output ports **81, 91** can be realized by any known coupling means to couple a resonator assembly

to an external source, such as a probe from a coaxial connector or iris from a waveguide port. Input and output ports **81, 91** can be located within the sidewall, the top end wall, or the bottom end wall of the enclosure **72.**

[0098] Microwave energy can be coupled from the inlet resonator assembly **92** through the input port **81,** to the optional intermediate resonator assemblies **93** via the above mentioned coupling means to the outlet resonator assembly **94** and to an external destination through the output port **80.**

[0099] In addition, tuning screws **74** and coupling screws **76** are located on the sidewalls of the enclosures **72.** A tuning screw **74** protrusion is used for resonant frequency adjustment and coupling screw **76** protrusion is used to generate orthogonal modes and to vary the degree of coupling between the two modes.

[0100] In general, tuning screws providing frequency adjustments are aligned orthogonally to each other and with the corresponding modes excited in the resonator assembly, but they may be located in different planes since the electromagnetic field pattern repeats itself at least twice in the resonator assemblies **92, 93** and **94.** Typically, tuning screws are located at the maximum point of the electric or magnetic field to maximize their effects. In this case, because the electromagnetic field repeats itself at least twice, the tuning screws can be located in different position on the resonator assembly without sacrificing tuning range. The coupling screw is generally located at a 45 degrees angle between the two excited modes.

[0101] Tuning screws can have different dimensions even within the same resonator assembly.

[0102] Also, the resonator assemblies of the filter assembly **80** can be arranged in a straight line or in a complete folded canonical structure, in principal there is no limitation on the arrangement of the resonator assemblies **92, 93, 94,** as far as performance is concerned.

[0103] Finally, various denting or machining techniques can also be applied in order to perturb the electromagnetic field. That is, it is contemplated that small pockets of dielectric material be removed from locations in the resonator element **58** where unwanted spurious modes have stronger electromagnetic field strength while desired modes (i.e. the dominant mode) have relatively weaker electromagnetic field strength. As a result, the undesirable spurious modes will resonate either at higher frequency or be removed. Typical approaches of removing dielectric material include cutting and drilling holes in the resonator element **58** as is conventionally known.

[0104] While the above description provides examples of the embodiments, it will be appreciated that some features and/or functions of the described embodiments are susceptible to modification without departing from the spirit and principles of operation of the described embodiments. Accordingly, what has been described above has been intended to be illustrative of the invention and non-limiting and it will be understood by persons skilled in the

art that other variants and modifications may be made without departing from the scope of the invention as defined in the claims appended hereto.

Claims

1. A resonator cavity for supporting a plurality of resonant modes and filtering electromagnetic energy, said resonator cavity comprising:

(a) a cavity defined by a top end wall, a bottom end wall and a sidewall, said cavity having a longitudinal axis along which the length of the cavity is defined;
(b) a resonator element having a top end and a bottom end, said resonator element positioned within the cavity along the longitudinal axis of the cavity along which the length of the resonator body is also defined;
(c) the resonator element also including a mounting flange for coupling the resonator element to the cavity at a mounting location along the length of the resonator element;
(d) the cavity and the resonator element having dimensions selected so that the electromagnetic energy associated with the resonator cavity is defined by an electromagnetic field pattern that substantially repeats itself at least twice along the length of the resonator; and

wherein the resonator element is only in physical contact with the cavity through the mounting flange at the mounting location where at least one resonant mode of the electromagnetic energy exhibits a local minima.

2. The resonator cavity of claim 1, wherein the electromagnetic field pattern substantially repeats itself twice along the length of the resonator and wherein the mounting location is located at the approximate midpoint of the length of the resonator element.

3. The resonator cavity of claim 1, wherein the electromagnetic field pattern substantially repeats itself three times along the length of the resonator and wherein the mounting location is located at one of: the approximate one third and the approximate two thirds along length of the resonator element.

4. The resonator cavity of claim 1, wherein the local minima resides within a plane that is orthogonal to the longitudinal axis of the cavity at the mounting location and wherein the mounting flange is coupled to the sidewall of the cavity along a circumferential area defined by a plane that is also orthogonal to the longitudinal axis of the cavity at the mounting location.

5. The resonator cavity of claim 1, wherein the mounting flange is formed integrally with the resonator element.

6. The resonator cavity of claim 1, wherein the mounting flange is ring shaped.

7. The resonator cavity of claim 1, wherein the mounting flange is oriented orthogonal to the longitudinal axis of the cavity.

8. The resonator cavity of claim 1, wherein a top space gap is formed between the top end of the resonator element and the top end wall of the cavity and a bottom space gap is formed between the bottom end of the resonator element and the bottom end wall of the cavity, and wherein the top and bottom space gaps provide thermal compensation in response to application of an external force to at least one of the top and bottom end walls.

9. The resonator cavity of claim 1, wherein the dielectric constant of the resonator element is less than 20.

10. The resonator cavity of claim 1, wherein the cavity is cylindrical and has a cross-section selected from the group consisting of: a circle, an ellipse and a polygon.

11. The resonator cavity of claim 1, wherein the resonator element is cylindrical and has a cross-section selected from the group consisting of: a circle, an ellipse and a polygon.

12. The resonator cavity of claim 1, wherein the resonator element is hollowed or pocked in at least one critical area for spurious-free improvements.

13. A resonator assembly comprising the resonator cavity of claim 1, wherein the top end wall, bottom end wall and the cylindrical sidewall of the cavity are defined by the inner surface of a lid and an enclosure and wherein:

(I) the lid has a cross section thickness defined by an outer diameter and an inner diameter, and wherein
(II) the enclosure having:

(A) a counter bore for receiving the mounting flange;
(B) a spring element **characterized by** a spring constant having a loaded inner diameter generally greater than the diameter of the resonator element, and a loaded outer diameter generally greater than the inner diameter of the lid and less than the diameter

of the counter bore; and

(C) the spring element being positioned between the lid and the mounting flange of the resonator element such that when the lid is forced onto the enclosure, a clamping force is provided to the resonator element to prevent micro-movements of the resonator element.

14. The resonator assembly of claim 13, wherein the spring element is made from metal or dielectric material.

15. The resonator assembly of claim 13, wherein the spring element is a wave washer element.

16. The resonator assembly of claim 13, wherein the enclosure and the lid are made from a metallic material and the dielectric resonator is made from a material having a dielectric constant less than 20.

17. A filter assembly comprising at least two resonator assemblies of claim 13, wherein the resonator assemblies further comprise at least one tuning screw and at least one coupling structure for coupling the at least two resonator assemblies.

18. The filter assembly of claim 17, further comprising an input port and an output port for coupling electromagnetic energy to and from an external source.

19. The filter assembly of claim 18, wherein the input and output ports can be located within the top or bottom end walls of the cavities.

20. The filter assembly of claim 17, wherein the coupling structures are selected from a group consisting of: irises, probes, metal posts, screws and shaping of the dielectric material.

21. The filter assembly of claim 17, wherein each resonator assembly is arranged in one of: a straight line and a complete folded canonical structure.

22. A resonator cavity for supporting a plurality of resonant modes and filtering electromagnetic energy, said resonator cavity comprising:

(a) a cavity defined by a top end wall, a bottom end wall and a cylindrical sidewall, said cavity having a longitudinal axis along which the length of the cavity is defined;
(b) a resonator element having:

(i) a resonator body defined by a top end and a bottom end, said resonator body positioned within the cavity along the longitudinal axis of the cavity along which the length of the resonator element is also defined; and
(ii) a mounting flange coupled around the resonator body at the bottom end of the resonator body and coupled to the bottom end wall of the cavity.

22. The resonator cavity of claim 22, wherein the mounting flange is coupled to the bottom end wall of the cavity using a mechanism selected from the group consisting of: bonding, clamping, and spring loaded clamping.

23. The resonator cavity of claim 22, wherein the dielectric constant of the resonator element is less than 20.

24. The resonator cavity of claim 22, wherein the resonator element and the cavity have a cross-section in the shape selected from one of the group comprising a circle, an ellipse and polygons.

25. The resonator cavity of claim 22, wherein the resonator element is hollowed or pocked in critical area for spurious-free and Q factor improvements.

26. The resonator cavity of claim 22, wherein a top space gap is formed between the top end of the resonator element and the top end wall of the cavity, and wherein the top space gap provides thermal compensation in response to application of an external force to the top end wall.
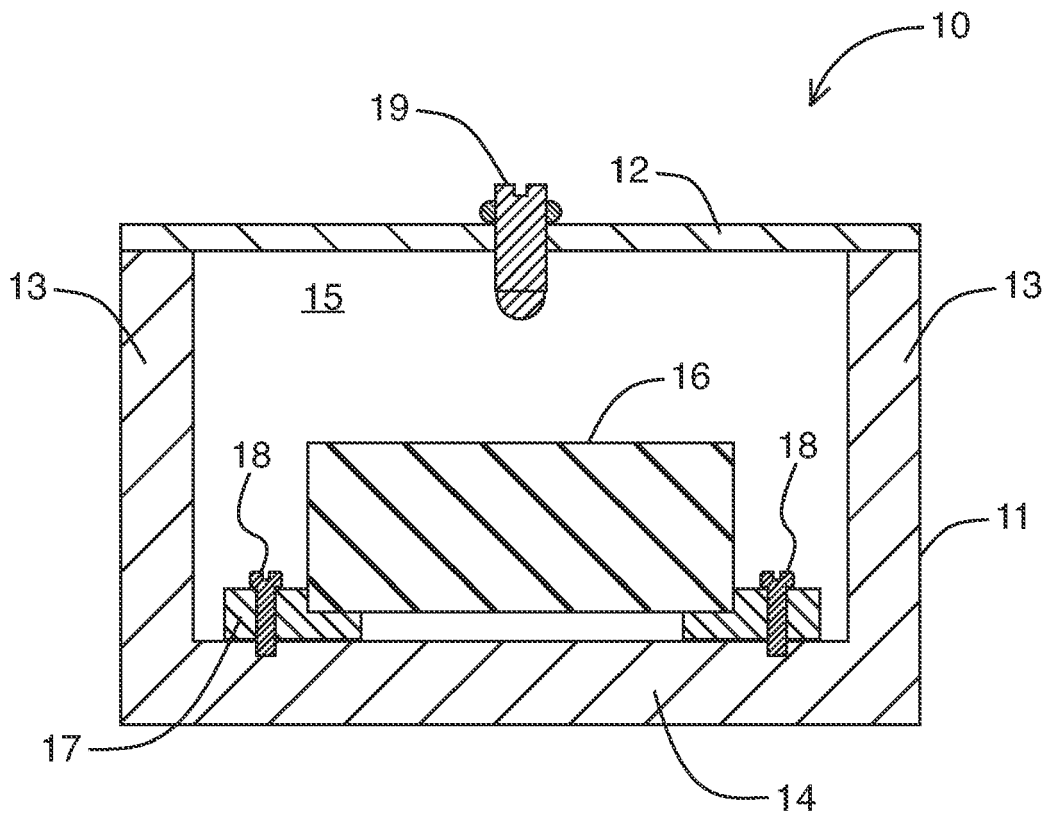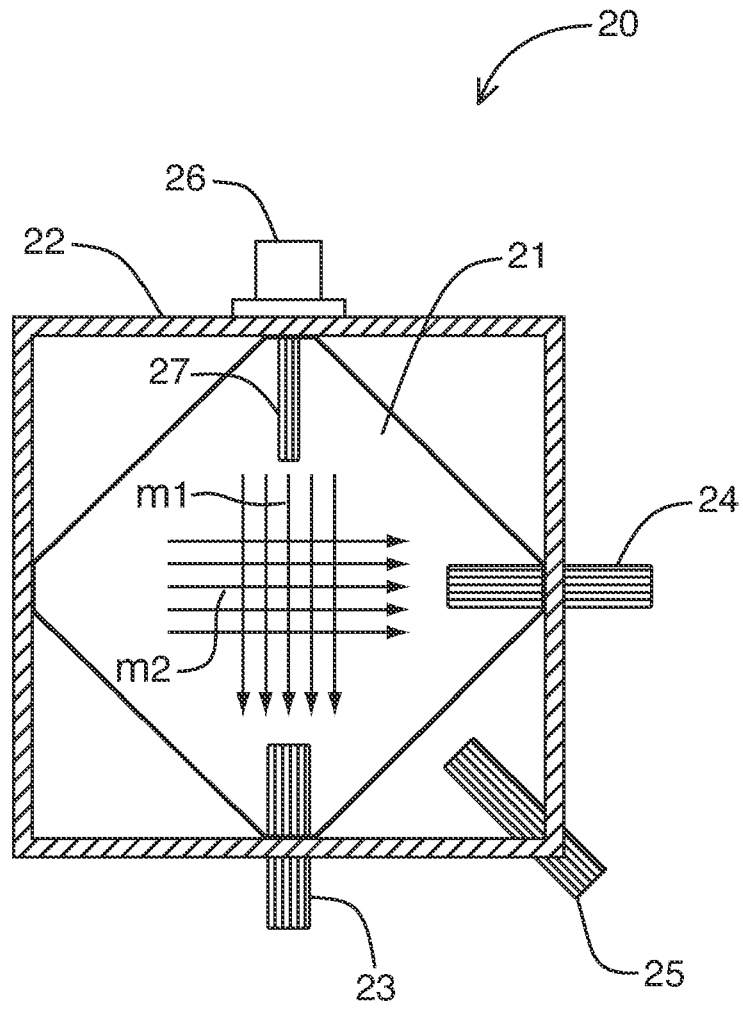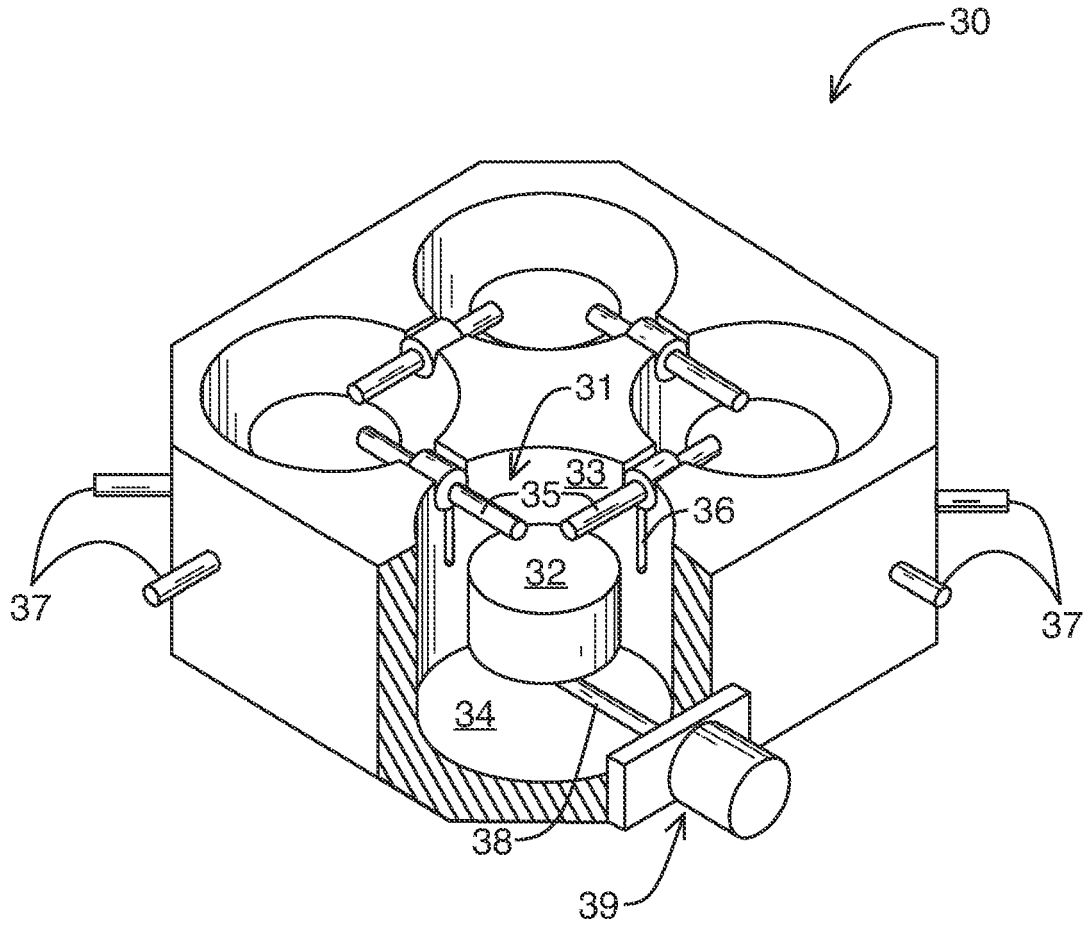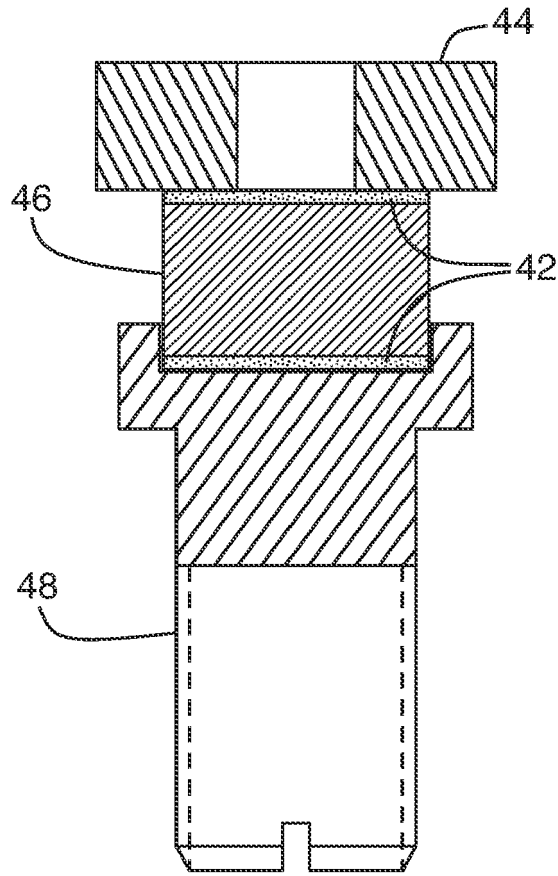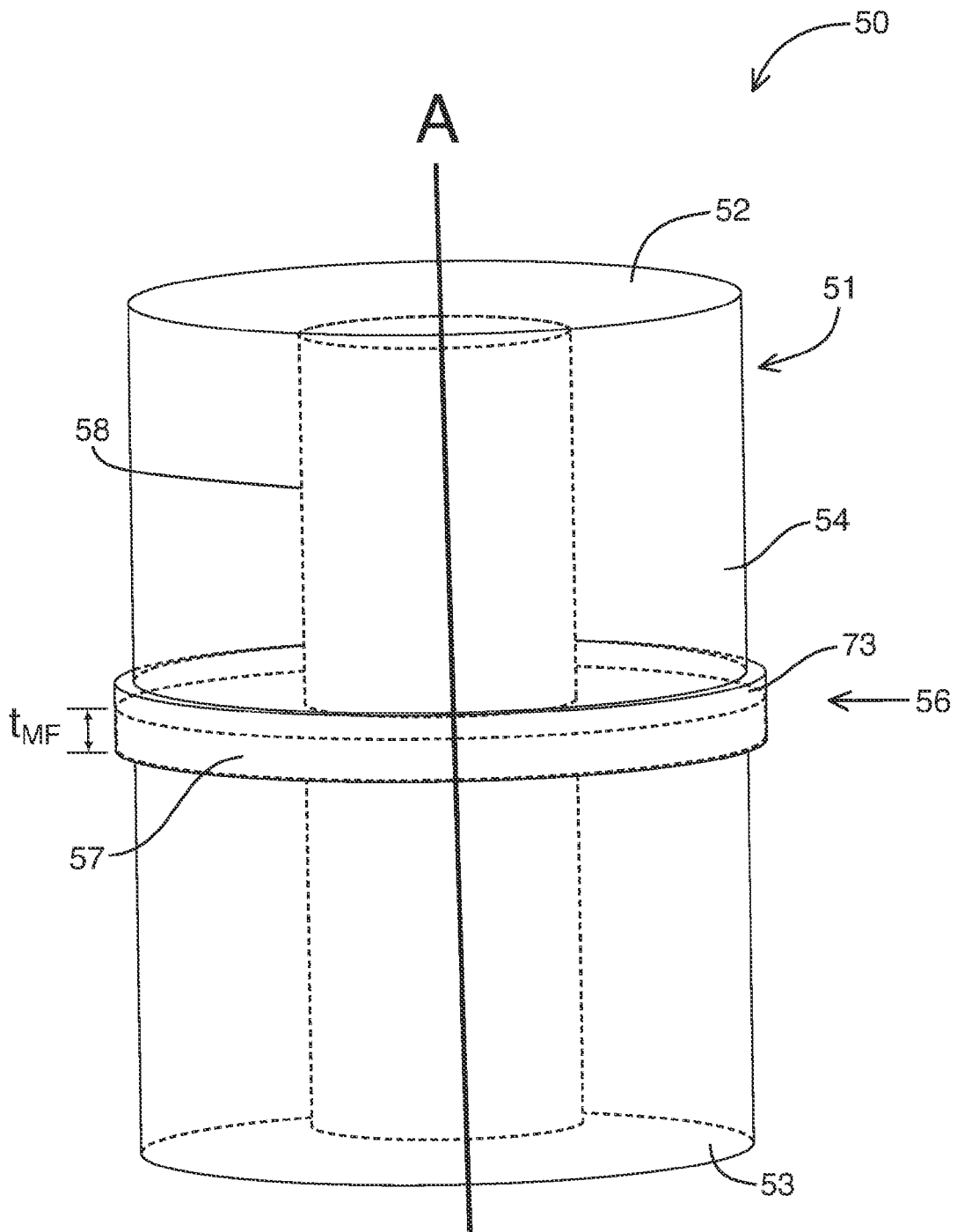
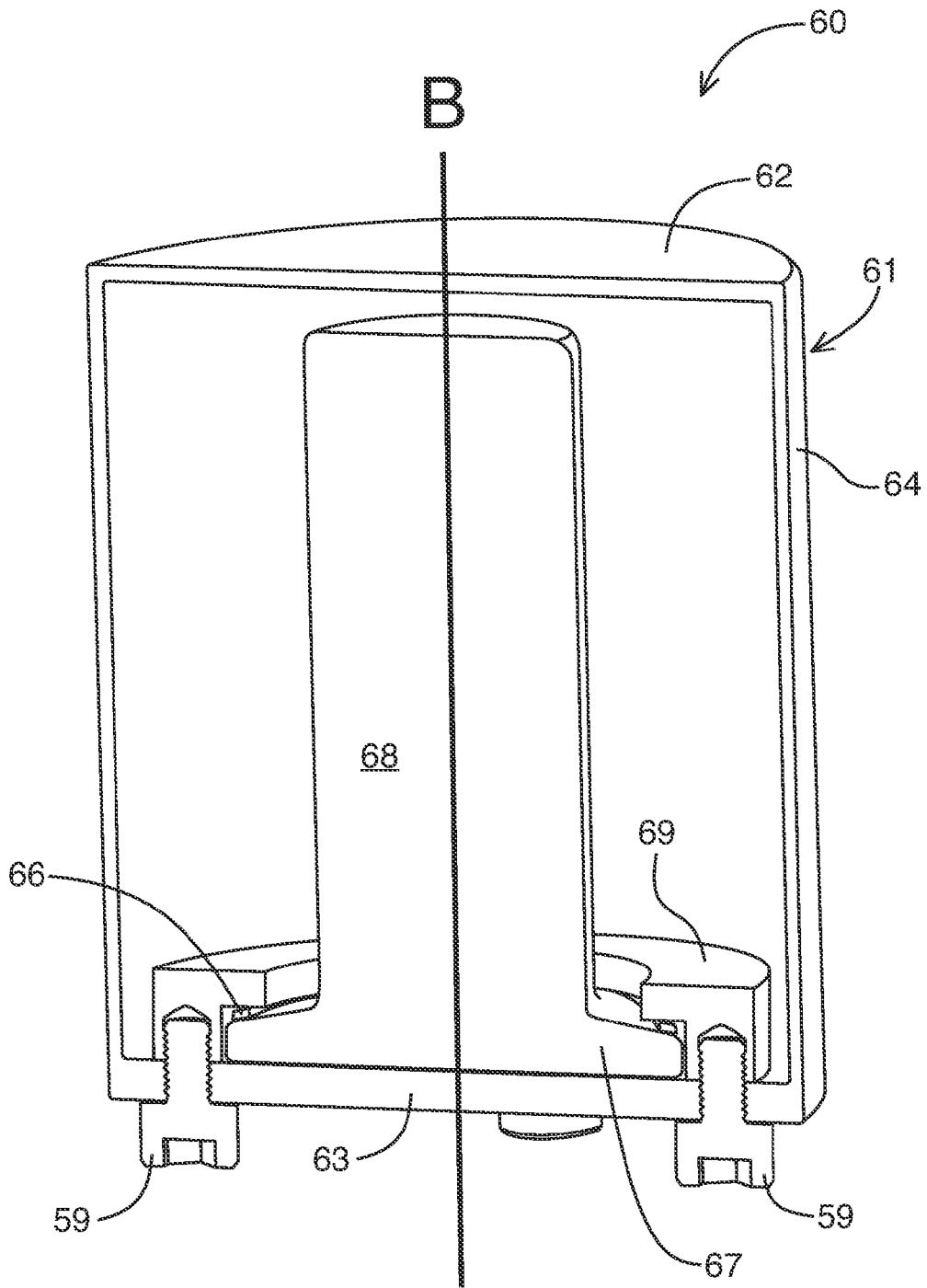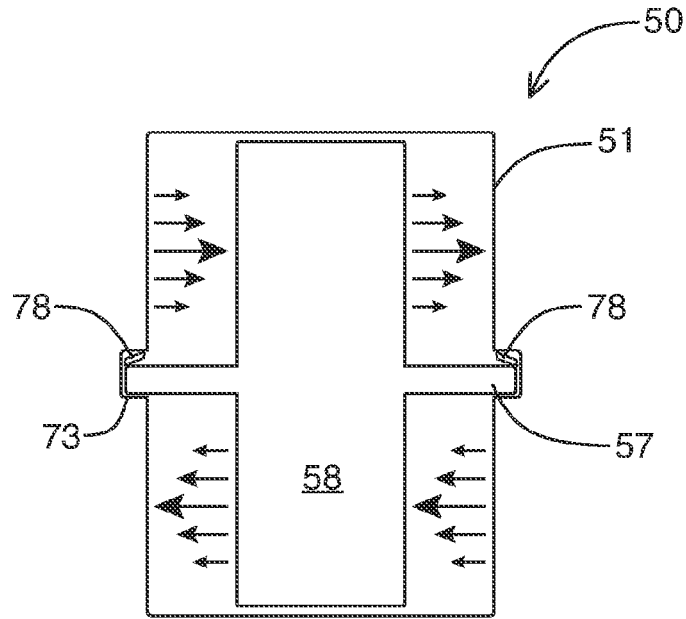FIG. 1
PRIOR ART

FIG. 2
PRIOR ART

FIG. 3
PRIOR ART

FIG. 4
PRIOR ART

FIG. 5

FIG. 6

FIG. 7A

FIG. 7B

FIG. 8

78

FIG. 9A

NO LOAD

d1

78

d2

FIG. 9B

LOAD

d1ᴵ

78

d2ᴵ
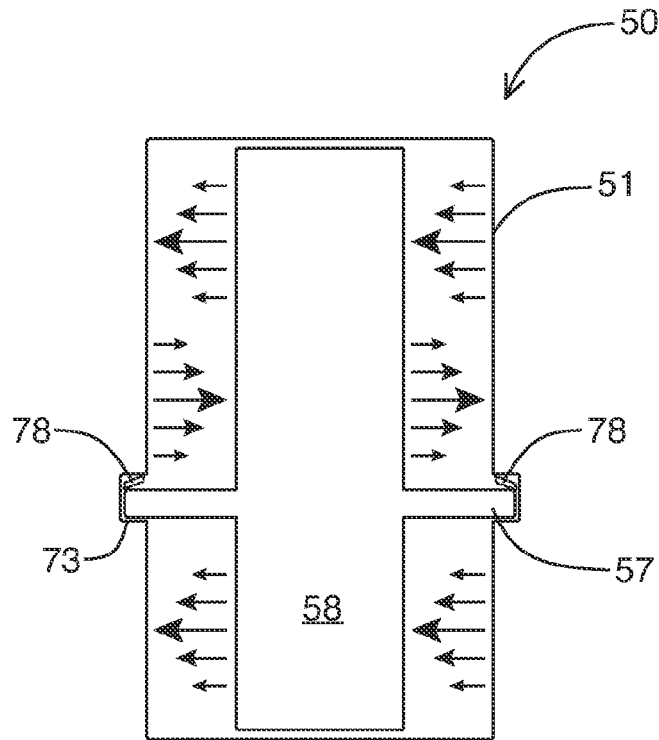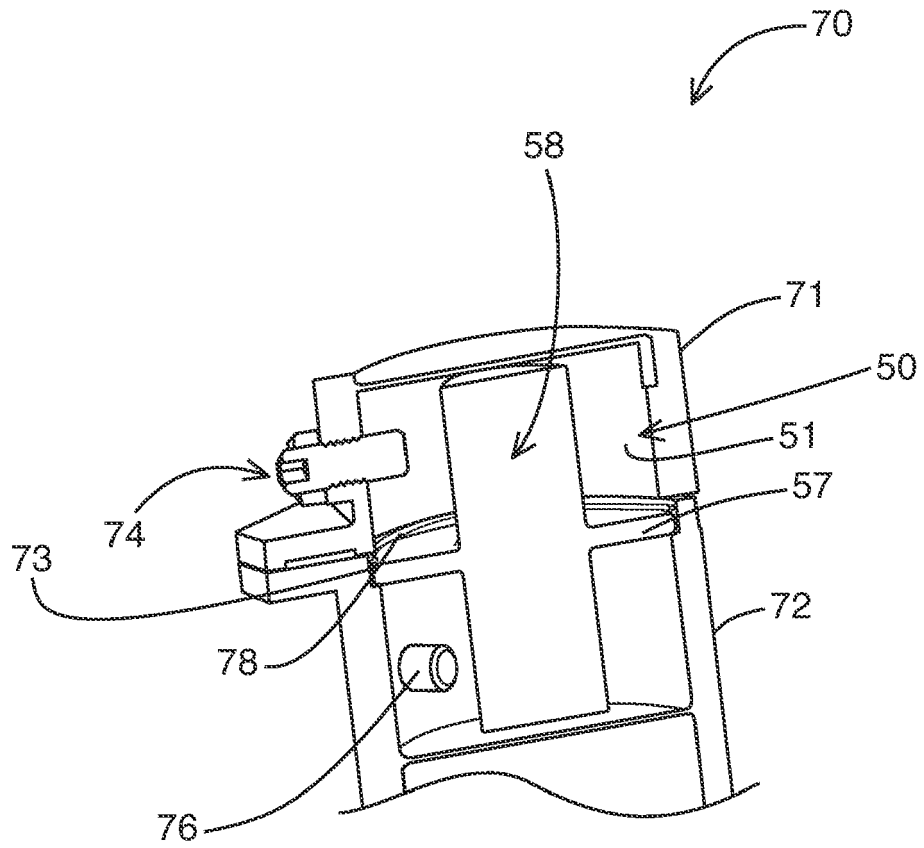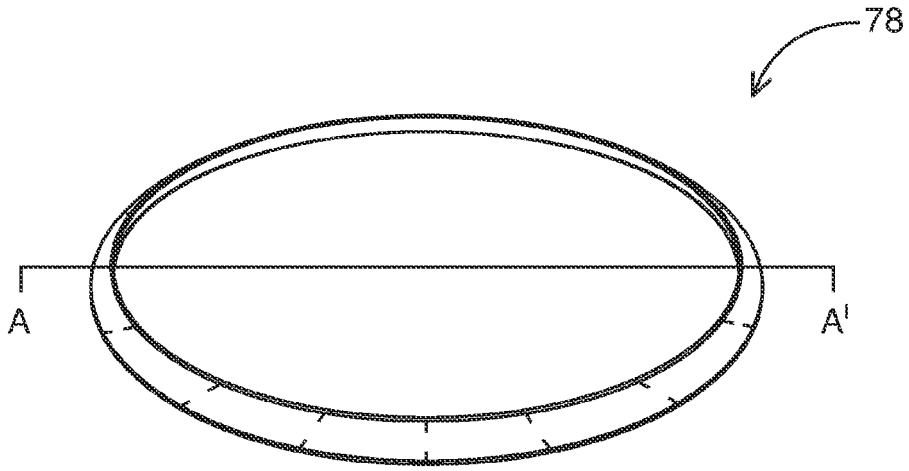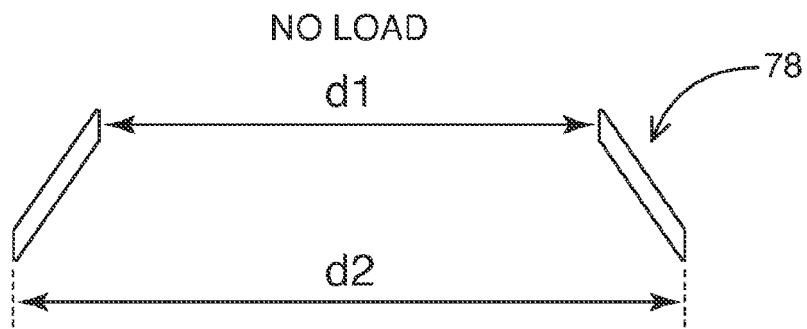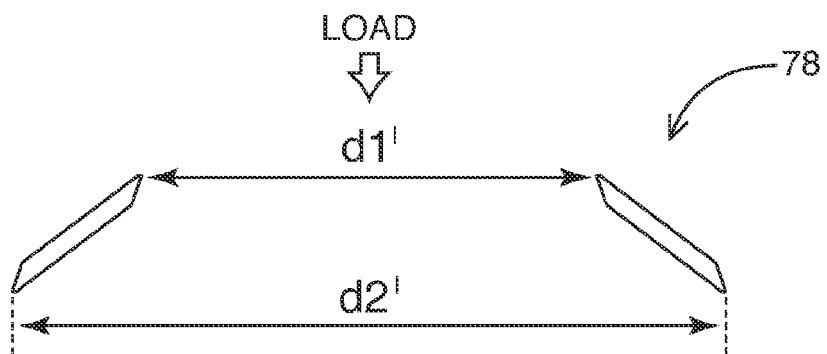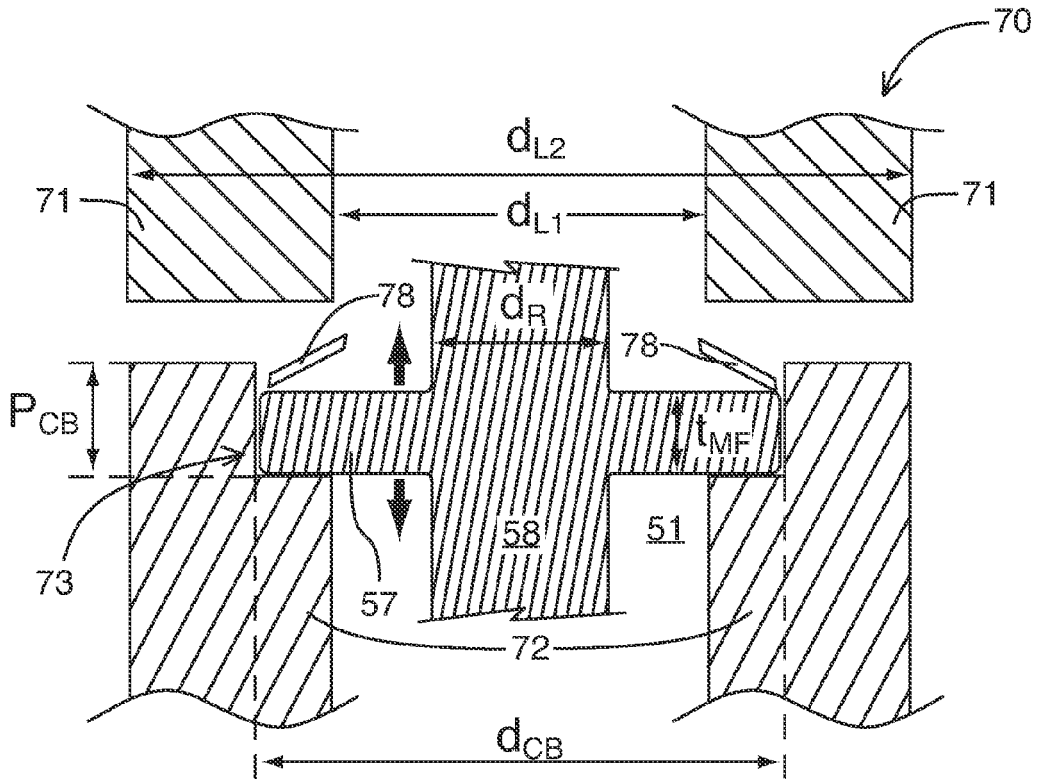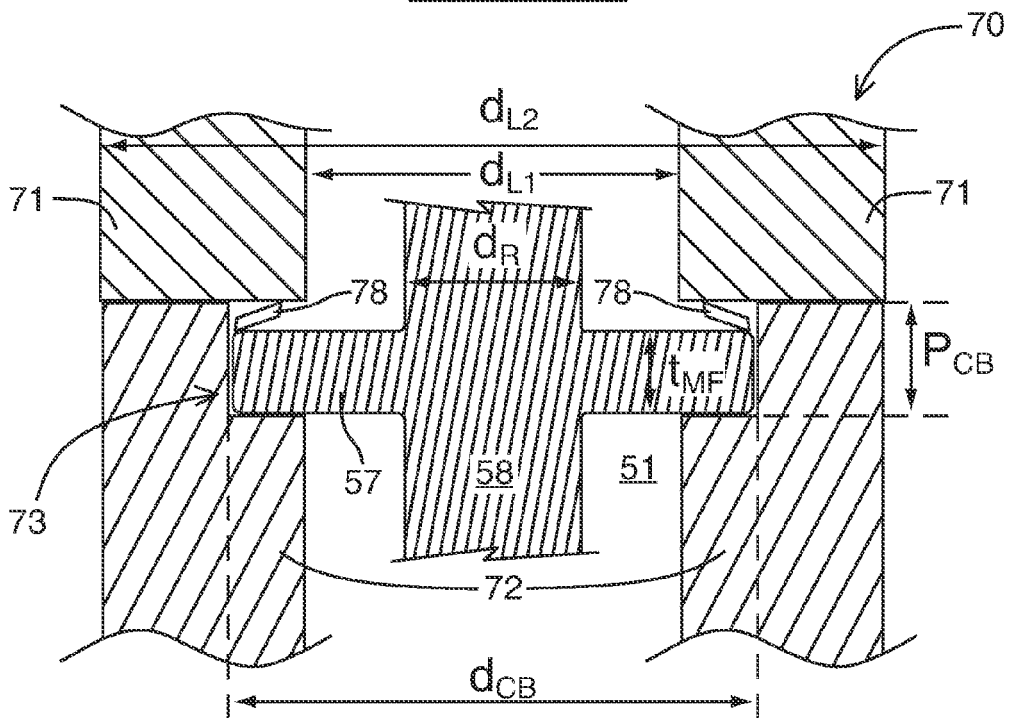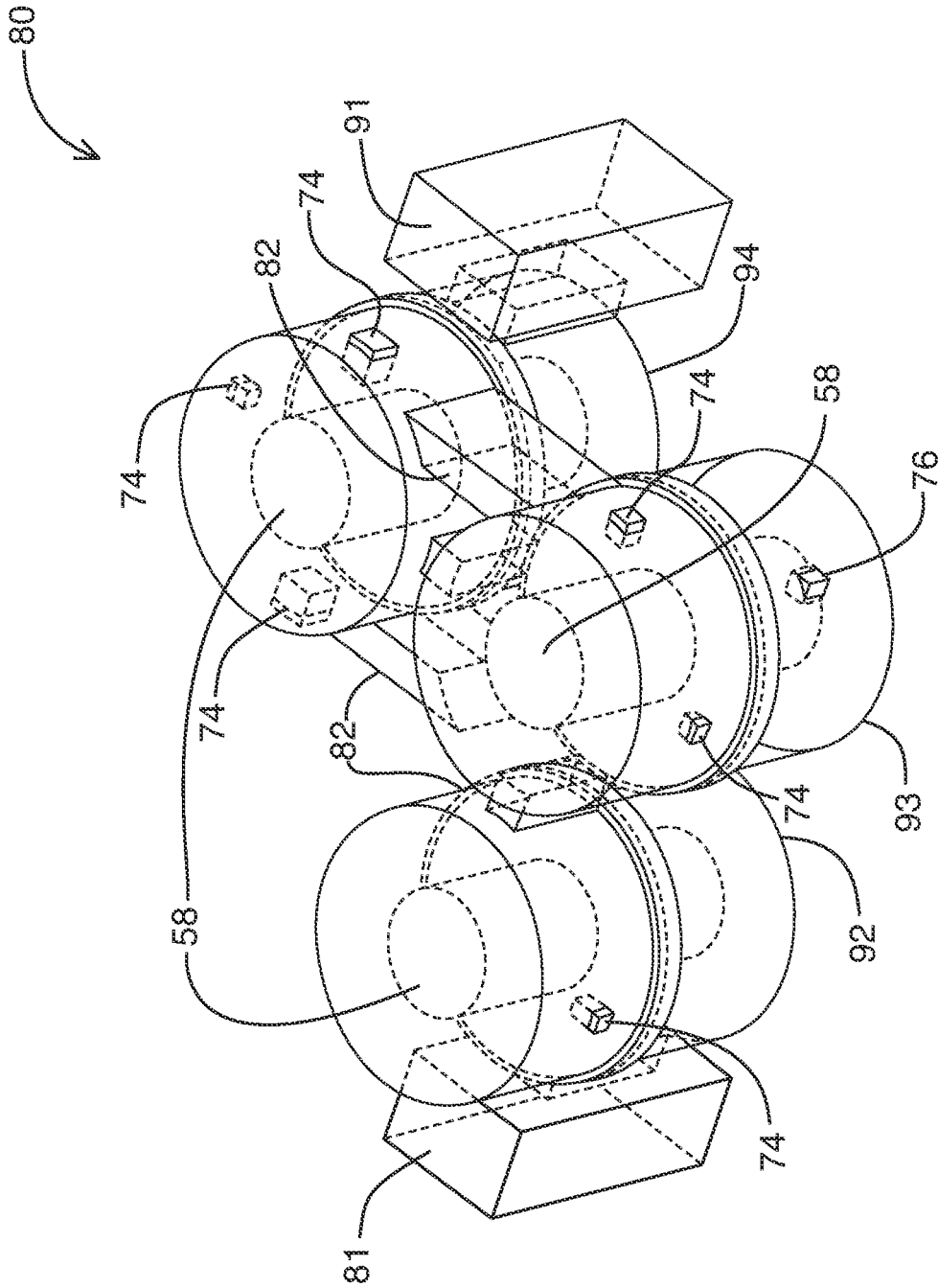
FIG. 9C

FIG. 10A

FIG. 10B

FIG. 11

EUROPEAN SEARCH REPORT

Application Number

EP 09 15 6511

DOCUMENTS CONSIDERED TO BE RELEVANT

Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
X	EP 1 104 044 A (MURATA MANUFACTURING CO [JP]) 30 May 2001 (2001-05-30)	1-12	INV. H01P7/10
Y	* column 5, line 29 - column 13, line 29 * * figures 1-25 * * abstract *	13-21	ADD. H01P1/205

X	WO 93/24970 A (POSEIDON SCIENT INSTR PTY LTD [AU]; UNIV WESTERN AUSTRALIA [AU]; IVANO) 9 December 1993 (1993-12-09)	1-12	
Y	* page 5, line 30 - page 7, line 13 * * page 14, line 22 - page 17, line 13 * * figures 1A,1B,12A-13B * * abstract *	13-21	

X	EP 0 173 545 A (UNIV WESTERN AUSTRALIA [AU]) 5 March 1986 (1986-03-05)	1-12	
Y	* page 3, line 14 - page 6, line 2 * * figure * * abstract *	13-21	

X	JP 56 165402 A (NIPPON ELECTRIC CO) 19 December 1981 (1981-12-19)	1-12	TECHNICAL FIELDS SEARCHED (IPC)
Y	* the whole document *	13-21	H01P

~~The present search report has been drawn up for all claims~~

Place of search	Date of completion of the search	Examiner
Munich	24 June 2009	von Walter, Sven-Uwe

1

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CLAIMS INCURRING FEES

The present European patent application comprised at the time of filing claims for which payment was due.

☐ Only part of the claims have been paid within the prescribed time limit. The present European search report has been drawn up for those claims for which no payment was due and for those claims for which claims fees have been paid, namely claim(s):

☐ No claims fees have been paid within the prescribed time limit. The present European search report has been drawn up for those claims for which no payment was due.

LACK OF UNITY OF INVENTION

The Search Division considers that the present European patent application does not comply with the requirements of unity of invention and relates to several inventions or groups of inventions, namely:

see sheet B

☐ All further search fees have been paid within the fixed time limit. The present European search report has been drawn up for all claims.

☐ As all searchable claims could be searched without effort justifying an additional fee, the Search Division did not invite payment of any additional fee.

☐ Only part of the further search fees have been paid within the fixed time limit. The present European search report has been drawn up for those parts of the European patent application which relate to the inventions in respect of which search fees have been paid, namely claims:

☒ None of the further search fees have been paid within the fixed time limit. The present European search report has been drawn up for those parts of the European patent application which relate to the invention first mentioned in the claims, namely claims:

1-21

☐ The present supplementary European search report has been drawn up for those parts of the European patent application which relate to the invention first mentioned in the claims (Rule 164 (1) EPC).

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**LACK OF UNITY OF INVENTION
SHEET B**

Application Number

EP 09 15 6511

The Search Division considers that the present European patent application does not comply with the requirements of unity of invention and relates to several inventions or groups of inventions, namely:

```
1. claims: 1-21

       A resonator cavity including a dielectric elongated
       resonator element mounted with a top and bottom space gap
       using a flange
                       ---


2. claims: 22-27

       A resonator cavity including a dielectric elongated
       resonator element mounted on the bottom end wall of the
       cavity using a flange
                       ---
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**ANNEX TO THE EUROPEAN SEARCH REPORT
ON EUROPEAN PATENT APPLICATION NO.**   EP 09 15 6511

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report.
The members are as contained in the European Patent Office EDP file on
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